

# HEF4070B

Quad 2-input EXCLUSIVE-OR gate

Rev. 4 — 27 March 2014

Product data sheet

## 1. General description

The HEF4070B is a quad 2-input EXCLUSIVE-OR gate. The outputs are fully buffered for the highest noise immunity and pattern insensitivity to output impedance.

It operates over a recommended  $V_{DD}$  power supply range of 3 V to 15 V referenced to  $V_{SS}$  (usually ground). Unused inputs must be connected to  $V_{DD}$ ,  $V_{SS}$ , or another input.

## 2. Features and benefits

- Fully static operation
- 5 V, 10 V, and 15 V parametric ratings
- Standardized symmetrical output characteristics
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$
- Complies with JEDEC standard JESD 13-B

## 3. Applications

- Logical comparators
- Parity checkers and generators

## 4. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
HEF4070BP	$-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$	DIP14	plastic dual in-line package; 14 leads (300 mil)	SOT27-1
HEF4070BT	$-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1



### 5. Functional diagram

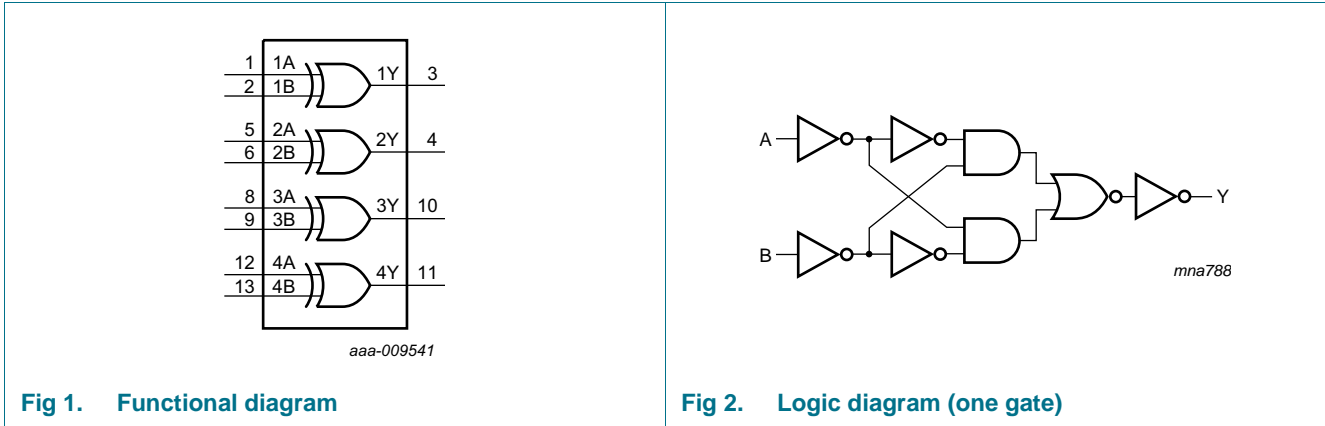


Fig 1. Functional diagram

Fig 2. Logic diagram (one gate)

### 6. Pinning information

#### 6.1 Pinning

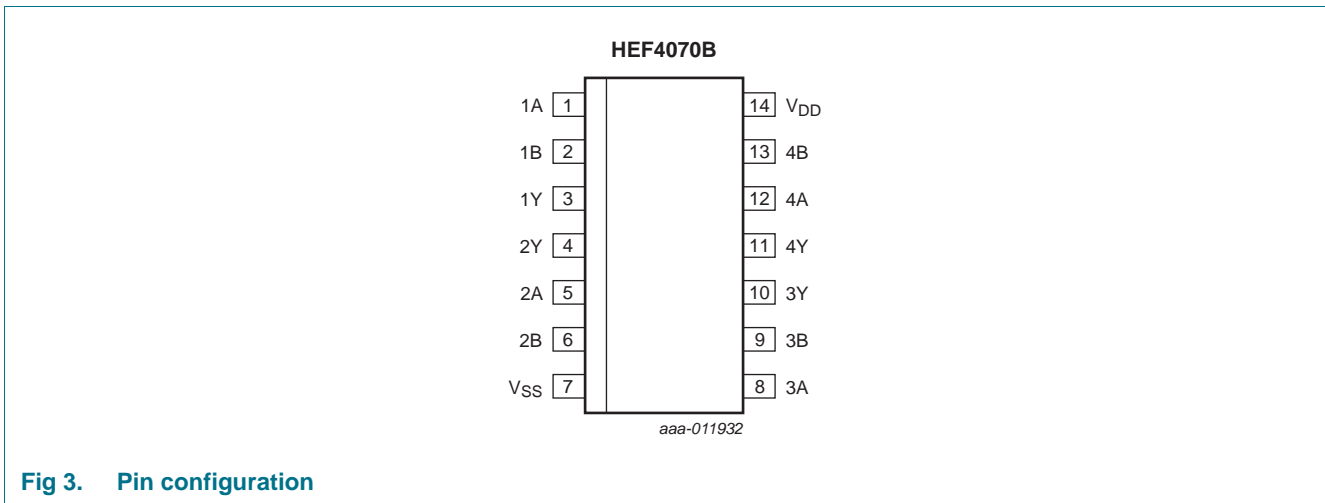


Fig 3. Pin configuration

#### 6.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1A, 2A, 3A, 4A	1, 5, 8, 12	data input
1B, 2B, 3B, 4B	2, 6, 9, 13	data input
1Y, 2Y, 3Y, 4Y	3, 4, 10, 11	data output
V <sub>SS</sub>	7	ground (0 V)
V <sub>DD</sub>	14	supply voltage

## 7. Functional description

Table 3. Functional table<sup>[1]</sup>

Input		Output
nA	nB	nY
L	L	L
L	H	H
H	L	H
H	H	L

[1] H = HIGH voltage level; L = LOW voltage level

## 8. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to  $V_{SS} = 0$  V (ground).

Symbol	Parameter	Conditions	Min	Max	Unit	
$V_{DD}$	supply voltage		-0.5	+18	V	
$I_{IK}$	input clamping current	$V_I < -0.5$ V or $V_I > V_{DD} + 0.5$ V	-	$\pm 10$	mA	
$V_I$	input voltage		-0.5	$V_{DD} + 0.5$	V	
$I_{OK}$	output clamping current	$V_O < -0.5$ V or $V_O > V_{DD} + 0.5$ V	-	$\pm 10$	mA	
$I_{I/O}$	input/output current		-	$\pm 10$	mA	
$I_{DD}$	supply current		-	50	mA	
$T_{stg}$	storage temperature		-65	+150	°C	
$T_{amb}$	ambient temperature		-40	+85	°C	
$P_{tot}$	total power dissipation	$T_{amb} = -40$ °C to +85 °C				
		DIP14	<sup>[1]</sup>	-	750	mW
		SO14	<sup>[2]</sup>	-	500	mW
P	power dissipation	per output	-	100	mW	

[1] For DIP14 packages: above  $T_{amb} = 70$  °C,  $P_{tot}$  derates linearly with 12 mW/K.

[2] For SO14 packages: above  $T_{amb} = 70$  °C,  $P_{tot}$  derates linearly with 8 mW/K.

## 9. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DD}$	supply voltage		3	15	V
$V_I$	input voltage		0	$V_{DD}$	V
$T_{amb}$	ambient temperature	in free air	-40	+85	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{DD} = 5$ V	-	3.75	$\mu$ s/V
		$V_{DD} = 10$ V	-	0.5	$\mu$ s/V
		$V_{DD} = 15$ V	-	0.08	$\mu$ s/V

## 10. Static characteristics

**Table 6. Static characteristics**

$V_{SS} = 0\text{ V}$ ;  $V_I = V_{SS}$  or  $V_{DD}$ ; unless otherwise specified

Symbol	Parameter	Conditions	$V_{DD}$	$T_{amb} = -40\text{ }^{\circ}\text{C}$		$T_{amb} = +25\text{ }^{\circ}\text{C}$		$T_{amb} = +85\text{ }^{\circ}\text{C}$		Unit
				Min	Max	Min	Max	Min	Max	
$V_{IH}$	HIGH-level input voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	3.5	-	3.5	-	3.5	-	V
			10 V	7.0	-	7.0	-	7.0	-	V
			15 V	11.0	-	11.0	-	11.0	-	V
$V_{IL}$	LOW-level input voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	-	1.5	-	1.5	-	1.5	V
			10 V	-	3.0	-	3.0	-	3.0	V
			15 V	-	4.0	-	4.0	-	4.0	V
$V_{OH}$	HIGH-level output voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	4.95	-	4.95	-	4.95	-	V
			10 V	9.95	-	9.95	-	9.95	-	V
			15 V	14.95	-	14.95	-	14.95	-	V
$V_{OL}$	LOW-level output voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	-	0.05	-	0.05	-	0.05	V
			10 V	-	0.05	-	0.05	-	0.05	V
			15 V	-	0.05	-	0.05	-	0.05	V
$I_{OH}$	HIGH-level output current	$V_O = 2.5\text{ V}$	5 V	-	-1.7	-	-1.4	-	-1.1	mA
		$V_O = 4.6\text{ V}$	5 V	-	-0.52	-	-0.44	-	-0.36	mA
		$V_O = 9.5\text{ V}$	10 V	-	-1.3	-	-1.1	-	-0.9	mA
		$V_O = 13.5\text{ V}$	15 V	-	-3.6	-	-3.0	-	-2.4	mA
$I_{OL}$	LOW-level output current	$V_O = 0.4\text{ V}$	5 V	0.52	-	0.44	-	0.36	-	mA
		$V_O = 0.5\text{ V}$	10 V	1.3	-	1.1	-	0.9	-	mA
		$V_O = 1.5\text{ V}$	15 V	3.6	-	3.0	-	2.4	-	mA
$I_I$	input leakage current		15 V	-	$\pm 0.3$	-	$\pm 0.3$	-	$\pm 1.0$	$\mu\text{A}$
$I_{DD}$	supply current	all valid input combinations; $I_O = 0\text{ A}$	5 V	-	1.0	-	1.0	-	7.5	$\mu\text{A}$
			10 V	-	2.0	-	2.0	-	15.0	$\mu\text{A}$
			15 V	-	4.0	-	4.0	-	30.0	$\mu\text{A}$
$C_I$	input capacitance			-	-	-	7.5	-	-	pF

## 11. Dynamic characteristics

**Table 7. Dynamic characteristics**

$T_{amb} = 25\text{ }^{\circ}\text{C}$ ; waveforms see [Figure 4](#); test circuit see [Figure 5](#); unless otherwise specified.<sup>[1]</sup>

Symbol	Parameter	Conditions	V <sub>DD</sub>	Extrapolation formula	Min	Typ	Max	Unit
t <sub>PHL</sub>	HIGH to LOW propagation delay	nA or nB to nY	5 V	58 ns + (0.55 ns/pF)C <sub>L</sub>	-	85	175	ns
			10 V	24 ns + (0.23 ns/pF)C <sub>L</sub>	-	35	75	ns
			15 V	21 ns + (0.16 ns/pF)C <sub>L</sub>	-	30	55	ns
t <sub>PLH</sub>	LOW to HIGH propagation delay	nA or nB to nY	5 V	43 ns + (0.55 ns/pF)C <sub>L</sub>	-	75	150	ns
			10 V	19 ns + (0.23 ns/pF)C <sub>L</sub>	-	30	65	ns
			15 V	17 ns + (0.16 ns/pF)C <sub>L</sub>	-	25	50	ns
t <sub>t</sub>	transition time		5 V <sup>[2]</sup>	10 ns + (1.00 ns/pF)C <sub>L</sub>	-	60	120	ns
			10 V	9 ns + (0.42 ns/pF)C <sub>L</sub>	-	30	60	ns
			15 V	6 ns + (0.28 ns/pF)C <sub>L</sub>	-	20	40	ns

[1] The typical value of the propagation delay and output transition time can be calculated with the extrapolation formula (C<sub>L</sub> in pF).

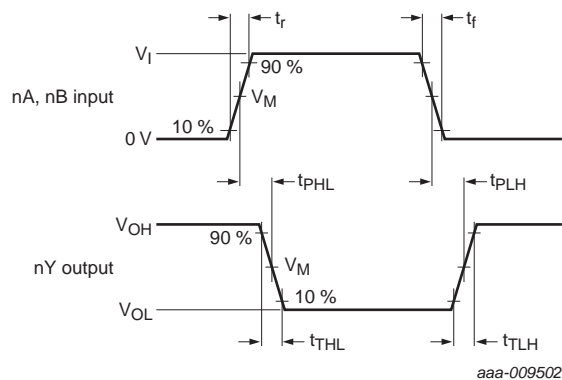
[2] t<sub>t</sub> is the same as t<sub>THL</sub> and t<sub>TLH</sub>.

**Table 8. Dynamic power dissipation**

V<sub>SS</sub> = 0 V; t<sub>r</sub> = t<sub>f</sub> ≤ 20 ns; T<sub>amb</sub> = 25 °C.

Symbol	Parameter	V <sub>DD</sub>	Typical formula	where:
P <sub>D</sub>	dynamic power dissipation	5 V	P <sub>D</sub> = 1100 × f <sub>i</sub> + Σ(f <sub>o</sub> × C <sub>L</sub> ) × V <sub>DD</sub> <sup>2</sup> (μW)	f <sub>i</sub> = input frequency in MHz;
		10 V	P <sub>D</sub> = 4900 × f <sub>i</sub> + Σ(f <sub>o</sub> × C <sub>L</sub> ) × V <sub>DD</sub> <sup>2</sup> (μW)	f <sub>o</sub> = output frequency in MHz;
		15 V	P <sub>D</sub> = 14400 × f <sub>i</sub> + Σ(f <sub>o</sub> × C <sub>L</sub> ) × V <sub>DD</sub> <sup>2</sup> (μW)	C <sub>L</sub> = output load capacitance in pF; Σ(f <sub>o</sub> × C <sub>L</sub> ) = sum of the outputs; V <sub>DD</sub> = supply voltage in V.

## 12. Waveforms



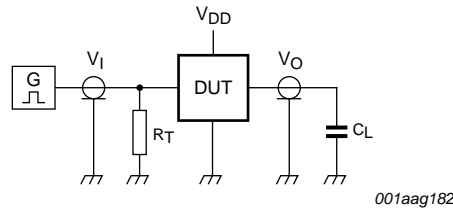
Measurement points are given in [Table 9](#).

Logic levels: V<sub>OL</sub> and V<sub>OH</sub> are typical output voltage levels that occur with the output load.

**Fig 4. Input to output propagation delay and output transition times**

Table 9. Measurement points

Supply voltage	Input	Output
$V_{DD}$	$V_M$	$V_M$
5 V to 15 V	$0.5V_{DD}$	$0.5V_{DD}$



Test data is given in [Table 10](#).

Definitions for test circuit:

DUT = Device Under Test.

$C_L$  = load capacitance including jig and probe capacitance.

$R_T$  = termination resistance should be equal to the output impedance  $Z_o$  of the pulse generator.

Fig 5. Test circuit

Table 10. Test data

Supply voltage	Input	Load
$V_{DD}$	$V_I$	$C_L$
5 V to 15 V	$V_{SS}$ or $V_{DD}$	$t_r, t_f$
		$\leq 20$ ns
		50 pF

13. Package outline

DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1

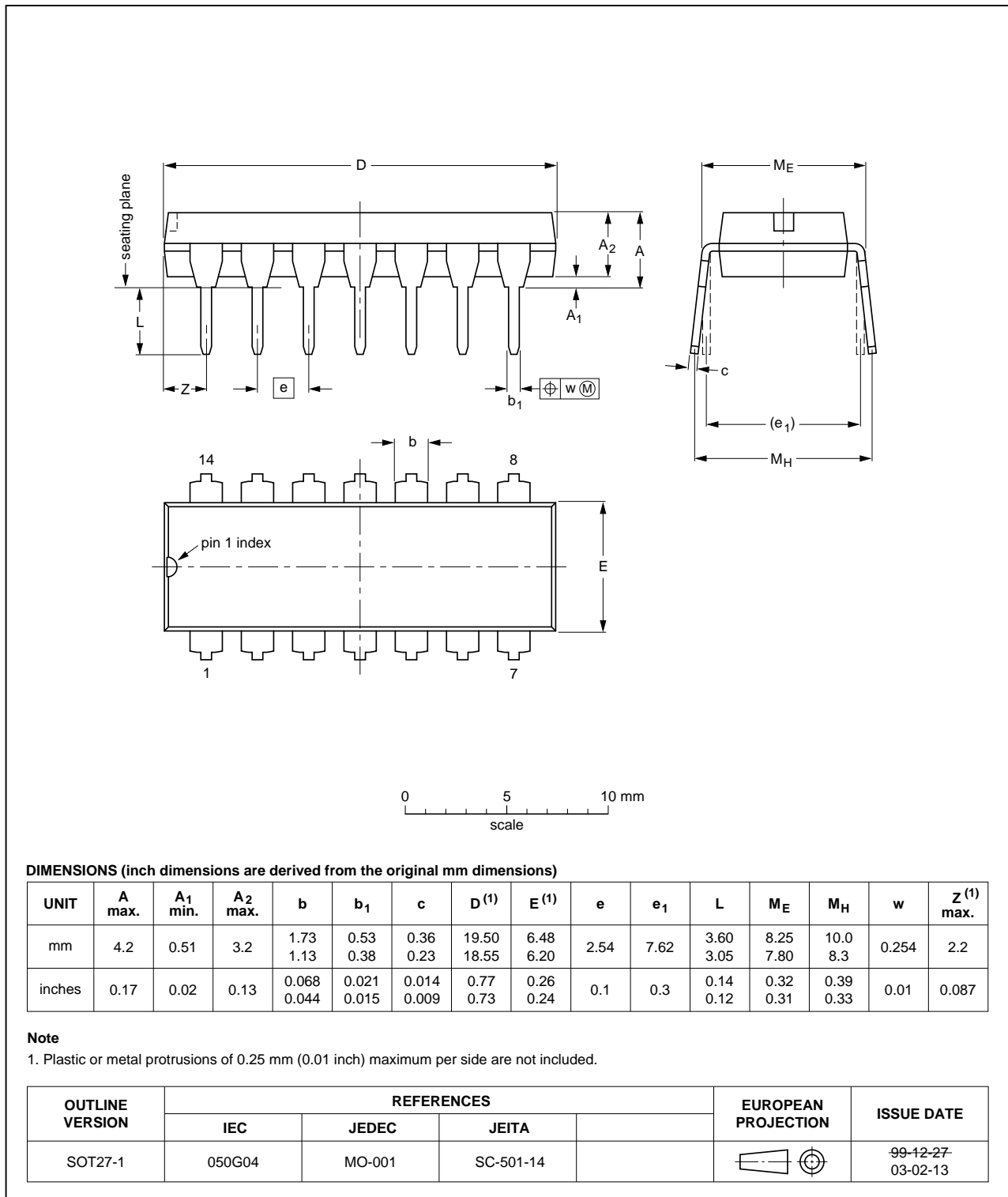


Fig 6. Package outline SOT27-1 (DIP14)

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

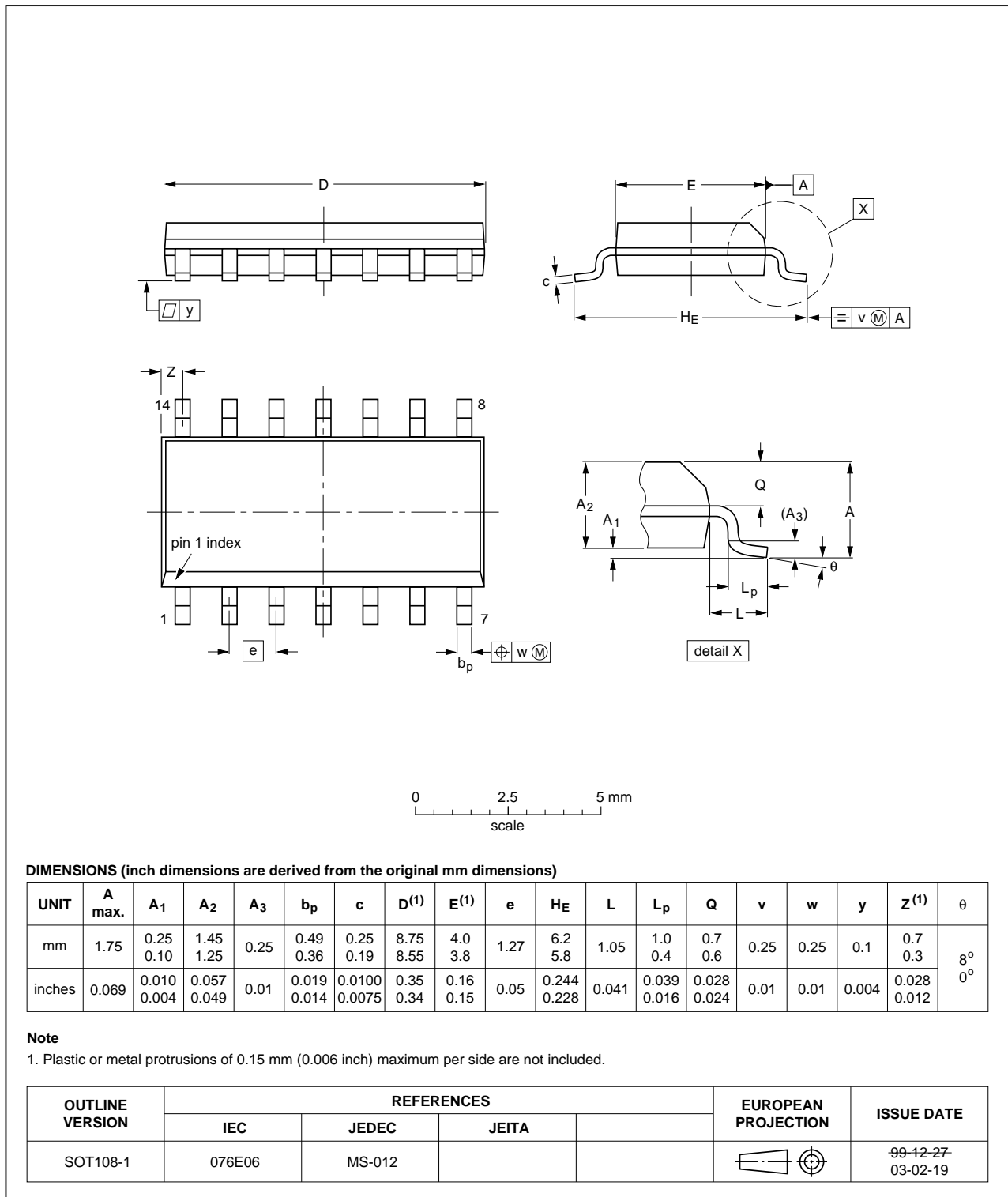


Fig 7. Package outline SOT108-1 (SO14)



## 14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
HEF4070B v.4	20140327	Product data sheet	-	HEF4070B_CNV v.3
Modifications:	<ul style="list-style-type: none"><li>• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li><li>• Legal texts have been adapted to the new company name where appropriate.</li></ul>			
HEF4070B_CNV v.3	19950101	Product specification	-	-

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### 15.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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